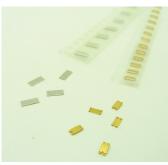
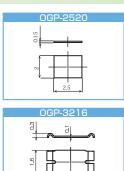
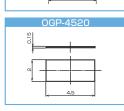
ON-BOARD PLATE / OGP-2520 ,-3216, -4520







Unit:mm

OGP configuration ensures reliable contact

Feature

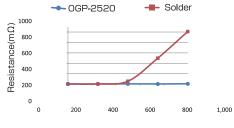
- OGP solves contact failure problems caused by solder flux.
- Better reliability compared with solder.
- Eliminates continuity failure caused by pattern scraping between a PCB and pogo pins and a PCB and a metal plate.
- OGP-2520 is 40 % or more downsized from OGP-4520. (Product size: 2.5 mm)
- Gold-plated OGP-3216 can be used as a partial.

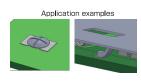
Material

- Base material: Brass Surface treatment: Sn reflow plating*(First plating: Cu plating)
- *Surface treatment for OGP-3216: Au/Ni plating on both sides.

Properties

Resistance measurement results







- ●Cost saving by automation!
- Parts are automatically counted by mounters.